Semiconductor Process

Model EV-X

Multi-process capable
Enhanced temperature profile

Compact
Class leading footprint

Energy Efficiency
Lowest Cost of Ownership

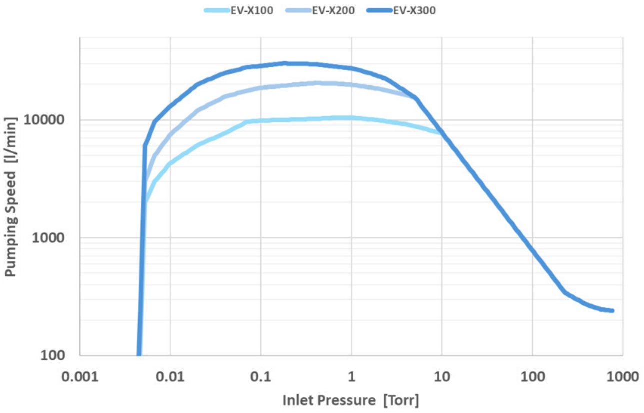
Design
Proven roots technology

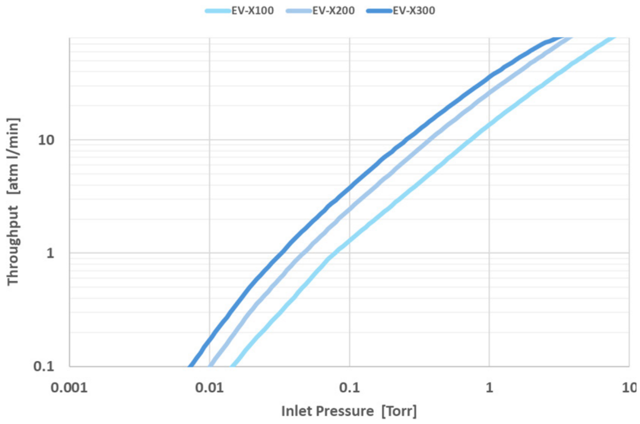
Applications
Oxide, poly, metal etch, strip, implant, HDP CVD

Pumping Speeds
10k, 20k, 30k l/min

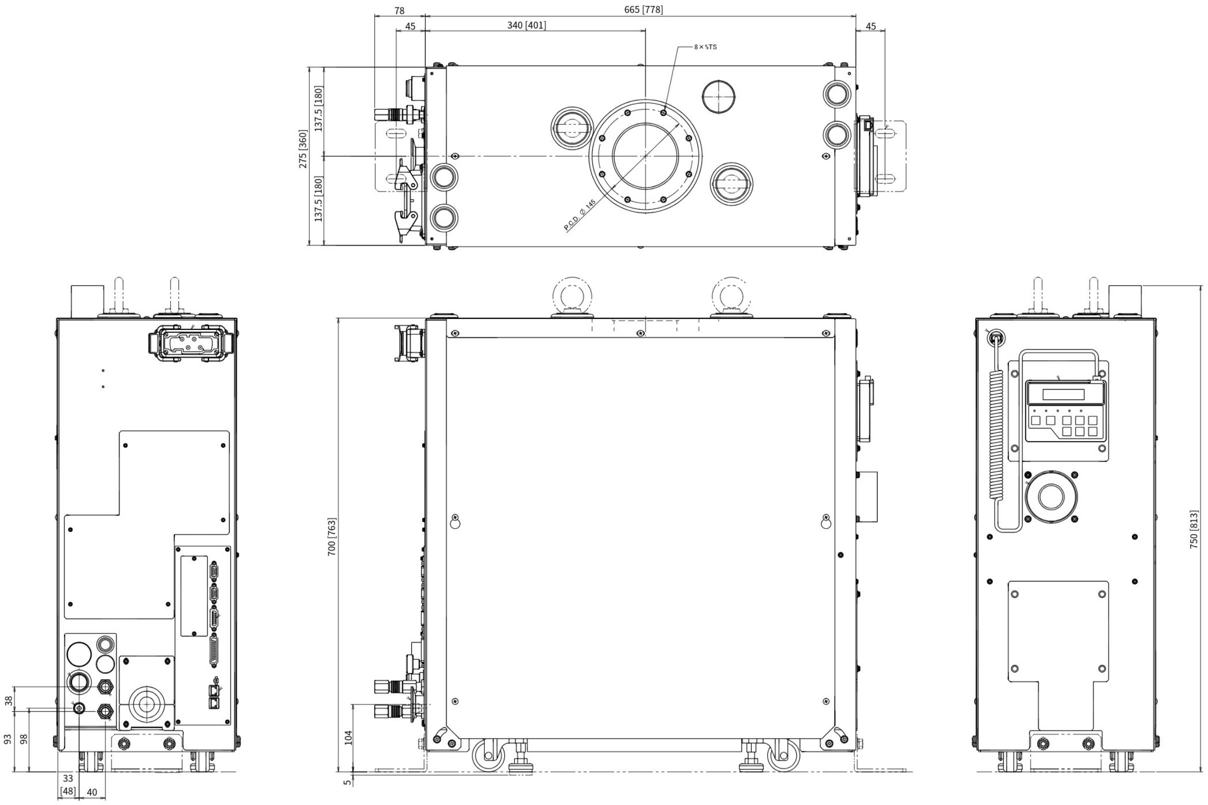
www.ebaratech.com

Specifications			EBARA Model EV-X		
Pump model			EV-X100N	EV-X200N	EV-X300N
Pumping speed		L/min	10,000	20,000	30,000
Ultimate pressure		Pa	0.5	0.5	0.5
Approx. power at ultimate pressure		kW	0.9	1.0	1.5
Connections	Gas inlet	-	ISO100 (Bolted)	ISO100 (Bolted)	ISO160 (Bolted)
	Gas outlet	-	NW40	NW40	NW40
Cooling water	Connection	-	Coupler (Rc1/4)	Coupler (Rc1/4)	Coupler (Rc1/4)
	Typical flow rate	L/min	1 - 4	1 - 4	2 - 4
N_2 purge gas ** max 84	Connection	-	1/4” Tube Fitting	1/4” Tube Fitting	1/4” Tube Fitting
	Typical flow rate	Pam^3/s	22-29**	22-29**	22-29**
Circuit protection (with optional heaters)		amps	30A (40A)	30A (40A)	40A (50A)
Power supply capacity (w/heaters)		kVA	6.4 (8.7)	6.4 (8.7)	7.6 (10.1)
Weight		kg	235	235	315
Dimensions (l x w x h)		mm	665 x 275 x 700	665 x 275 x 700	778 x 360 x 763





Dimensions EV-X100/200, [300]



Ahead Beyond